

**BALL LIMITING METALLURGY, INTERCONNECTION STRUCTURE  
INCLUDING THE SAME, AND METHOD OF FORMING AN  
INTERCONNECTION STRUCTURE**

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**ABSTRACT OF THE DISCLOSURE**

10 A ball-limiting metallurgy includes a substrate, a  
barrier layer formed over the substrate, an adhesion layer  
formed over the barrier layer, a first solderable layer  
formed over the adhesion layer, a diffusion barrier layer  
formed over the adhesion layer, and a second solderable  
layer formed over the diffusion barrier layer.